

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1.-3. (CANCELED)

Claim 4. (NEW) An information processing device comprising:

    a heat conductive element;

    a processor in thermal communication with said heat conductive element, wherein said processor generates heat when energized, and wherein said heat conductive element dissipates heat generated by said processor;

    a circuit board comprising a mounting area, wherein said processor is mounted at said mounting area; and

    a compressible element,

    wherein the circuit board is between the compressible element and the processor.

Claim 5. (NEW) The information processing device of claim 4 wherein the information processing device is a cartridge.

Claim 6. (NEW) The information processing device of claim 4 wherein the compressible element pushes the circuit board and the processor toward the heat conductive element.

Claim 7. (NEW) The information processing device of claim 4 wherein the heat conductive element is a heat dissipation plate.

Claim 8. (NEW) The information processing device of claim 4 wherein the heat conductive element comprises aluminum.

Claim 9. (NEW) The information processing device of claim 4 wherein the compressible element comprises silicon rubber.

Claim 10. (NEW) The information processing device of claim 4 further comprising an electrical contact at an edge region of the circuit board.

Claim 11. (NEW) The information processing device of claim 4 wherein the circuit board is a printed circuit board.

Claim 12. (NEW) The information processing device of claim 4 further comprising a ROM on the circuit board.

Claim 13. (NEW) The information processing device of claim 4 further comprising a heat dissipating material between the heat conductive element and the processor, wherein the heat dissipating material directly contacts the processor and the heat conductive element.

Claim 14. (NEW) The information processing device of claim 13 wherein the heat dissipating material is formed from a non-solid material.

Claim 15. (NEW) The information processing device of claim 4 wherein the compressible element comprises an elastic material.

Claim 16. (NEW) The information processing device of claim 4 wherein the heat dissipating material comprises silicon rubber.

Claim 17. (NEW) The information processing device of claim 4 wherein the processor is a microprocessor.

Claim 18. (NEW) The information processing device of claim 4 further comprising a plurality of pins coupled to the processor, the pins being perpendicular to the orientation of the circuit board.

Claim 19. (NEW) An information processing device comprising:

- a heat conductive element;
- a processor in thermal communication with said heat conductive element, wherein said processor generates heat when energized, and wherein said heat conductive element dissipates heat generated by said processor;
- a circuit board comprising a mounting area, wherein said processor is mounted at said mounting area;
- a heat dissipating material between the heat conductive element and the processor, wherein the heat dissipating material directly contacts the heat conductive element and the processor; and
- an insertion plug including an electrical contact formed at an end region of the circuit board.

Claim 20. (NEW) The information processing device of claim 19 wherein the heat conductive element is a plate.

Claim 21. (NEW) The information processing device of claim 19 wherein the heat dissipating material has a heat conductance rate of 1 W/m·K or more.

Claim 22. (NEW) The information processing device of claim 19 wherein the heat dissipating material is formed from a non-solid material.

Claim 23. (NEW) The information processing device of claim 19 further comprising a plurality of pins coupled to the circuit board, the plurality of pins oriented perpendicular to the orientation of the circuit board.

Claim 24. (NEW) The information processing device of claim 19 wherein the heat conductive element comprises aluminum.

Claim 25. (NEW) The information processing device of claim 19 wherein the heat dissipating material comprises silicon rubber.

Claim 26. (NEW) The information processing device of claim 19 wherein the information processing device is in the form of a cartridge.

Claim 27. (NEW) The information processing device of claim 19 wherein the circuit board is a printed circuit board.

Claim 28. (NEW) The information processing device of claim 19 further comprising a biasing element adapted to push the circuit board towards the heat conductive element.

Claim 29. (NEW) The information processing device of claim 19 further comprising a housing configured to protect the processor.

Claim 30. (NEW) The information processing device of claim 19 wherein the heat conductive element is in the form of a plate, and wherein the information processing device further comprises a plurality of pins coupled to the processor.